



揚博科技股份有限公司 Ampoc Far-East Co., Ltd.

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Investor Conference

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01

Ampoc Profile

Ampoc Profile



Since
1976年

Capital
12.68 Million

Revenue
36.58 Million

Employee
350人

1980-1990

- Ampoc was founded with initial registered capital of NT\$1 million;
- TCM Japan established TTCM in CHUNG-LI industrial zone for PCB wet process equipment manufacture. Ampoc invested TTCM and obtained global exclusive distribution ship excluding Japan.

2001-2010

- Company name changed as AMPOC FAR-EAST CO., LTD., capital increased to NT\$ 0.9 Billion.
- Ampoc (2493) was listed on the Taiwan Stock Exchange on 01/23/2002.

2021- now

- ESG task force established.
- ECO Heat exchange System developed.
- 2023 new purchase of Nanyuan Road factory for future business development.
- Establishment of a Thailand subsidiary in 2025.

1976- Establishment

1991-2000

- Ampoc purchased the office in Taipei as headquarters.
- Ampoc was approved as IPO.
- Ampoc merged TTCM.

2011-2020

- “Ampoc Wing” was developed and shipped to customer for production usage.
- HK subsidiary was approved by the board of directors.
- Ampoc Shanghai was invested by HK subsidiary.



02

Company Status

Company Status



~Ampoc is dedicated to serving the electronics industry, actively positioning itself as a vital bridge in the information and electronics sector~



MR. RONALD SU
(CEO & CHAIRMAN)



- 2 divisions**
- Manufacturing Management Division
 - Business Management Division



- 4 cores**
- Advanced manufacture
 - Hi-tech R&D
 - Advanced semiconductor process
 - Energy saving and carbon reduction



- 9 mindsets**
- Quality first
 - Innovation
 - profession
 - Process improvement
 - Engagement management
 - International marketing
 - Service first
 - Social responsibility
 - Sustainability



- 3 technologies**
- Ampoc Wing
 - Ampoc ECO
 - Ampoc 7A

The background of the slide features a soft-focus image of white clouds against a light blue sky. Overlaid on this are several blue geometric shapes: a large blue triangle in the top-left corner, a smaller blue triangle in the bottom-right corner, and a dark blue downward-pointing triangle on the left side that contains the number '03'.

03

Financial Information



2023~2025H1 Consolidated Balance sheet

Unit: NT\$ thousands (Except EPS: NT\$)

Item	Year	2023	2024	2025 H1
Net Revenue		3,354,285	3,657,780	1,837,898
Gross profit		1,219,708	1,236,832	566,848
Gross margin(%)		36.36	33.81	30.84
Operating income		836,161	818,984	355,252
Net income after tax		690,310	692,598	227,822
EPS		6.03	6.05	1.99



2023~2025H1 Consolidated Income statement

Unit: NT\$ thousands (Except EPS: NT\$)

Item	Year	2023	2024	2025 H1
Current Assets		3,869,784	3,286,628	3,691,087
Non-current Assets		1,113,823	1,137,382	1,172,595
Total Assets		4,983,607	4,424,010	4,863,682
Current Liabilities		1,709,646	1,127,374	1,847,726
Non-current Liabilities		273,407	147,527	125,937
Total Liabilities		1,983,053	1,274,901	1,973,663



2023~2025H1 Financial Analysis

Item	Year	2023	2024	2025 H1
Debt Ratio(%)		39.79	28.82	40.58
Current Ratio(%)		226.35	291.53	199.76
Average Inventory Turnover(Times)		1.86	2.54	2.87
Return on Equity (%)		23.95	22.52	7.54



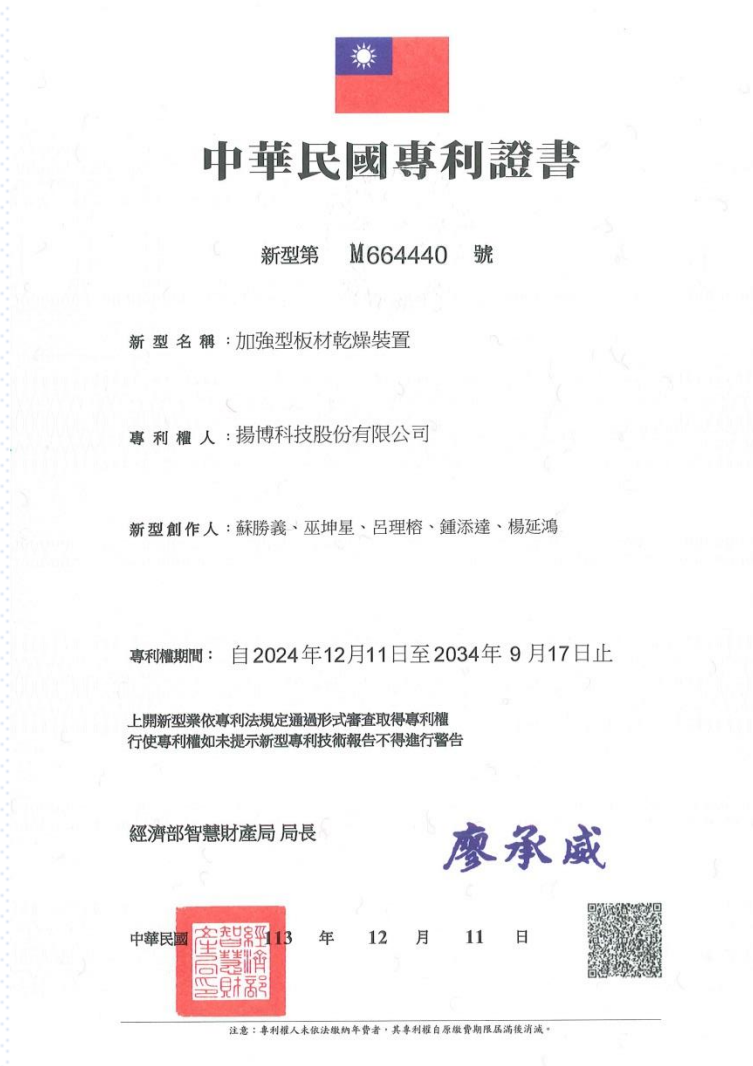
04

Own Brand Equipment - Introduction and Prospect



Own Brand Equipment Introduction

PATENT OF AMPOC SUPER DRY SYSTEM



AMPOC SUPER DRY SYSTEM

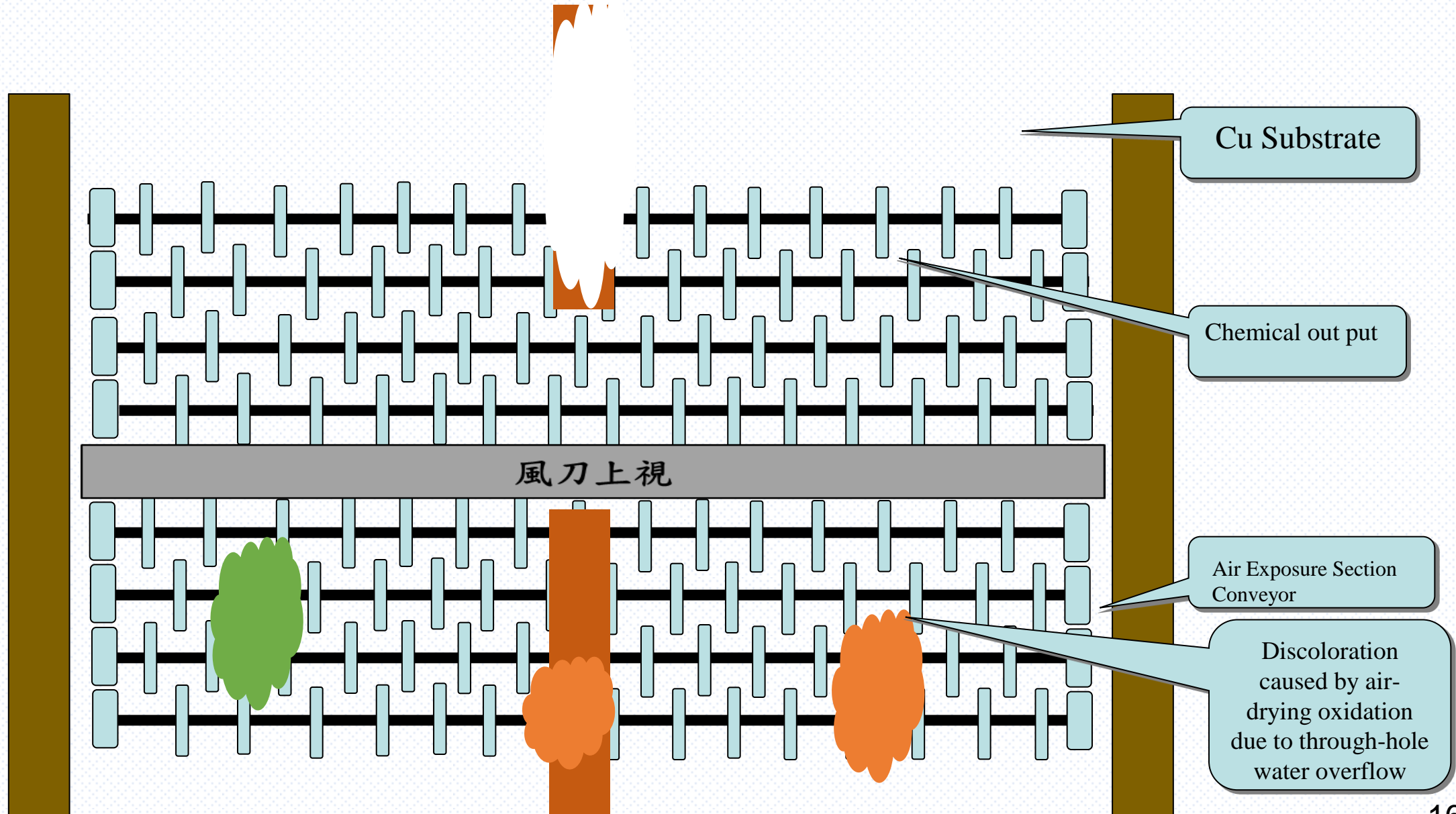
1. Purpose

To completely remove residual moisture inside the holes, especially for high aspect ratio holes, in order to prevent oxidation and quality degradation.

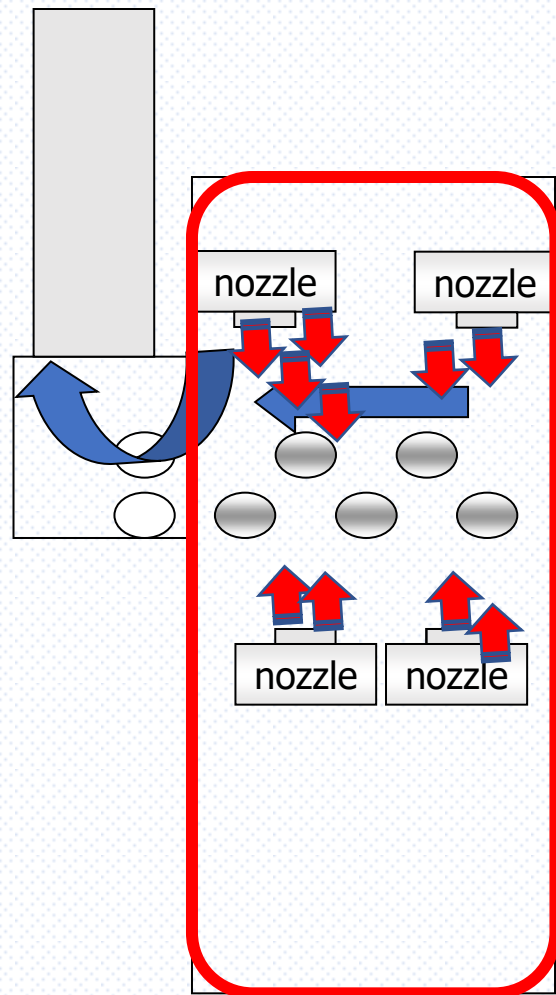
2. Technical Details

- Utilizes clean, dry air that has undergone special treatment to remove moisture and particles.
- Maintains an extremely low dew point to ensure effective drying.
- Capable of penetrating deep holes or micro-via structures to thoroughly eliminate moisture.
- Helps prevent oxidation and enhances the quality and reliability of via connections.

TOP VIEW

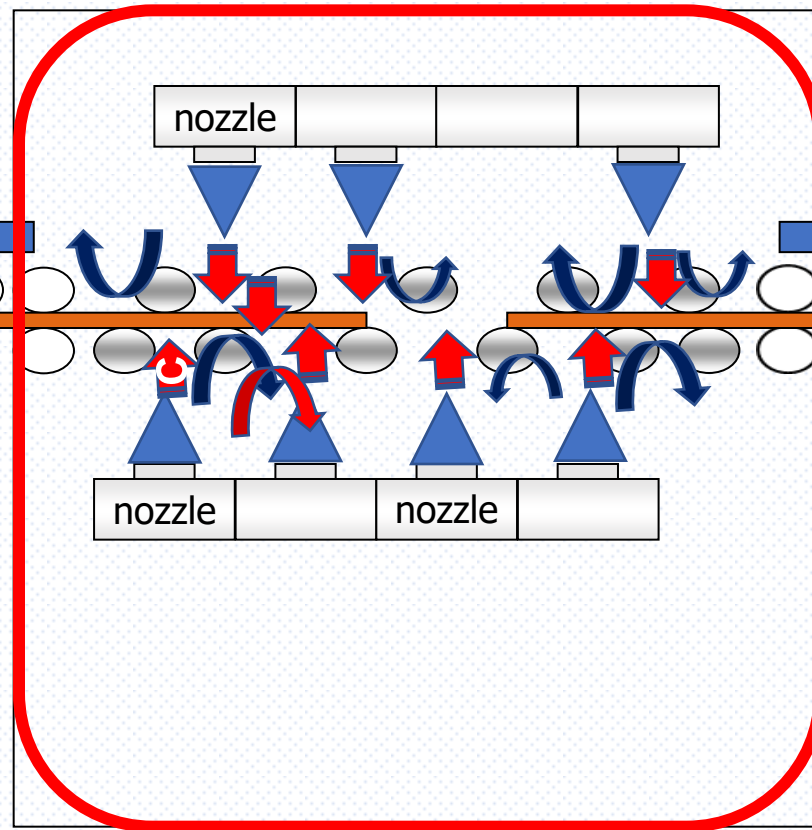


exhaust



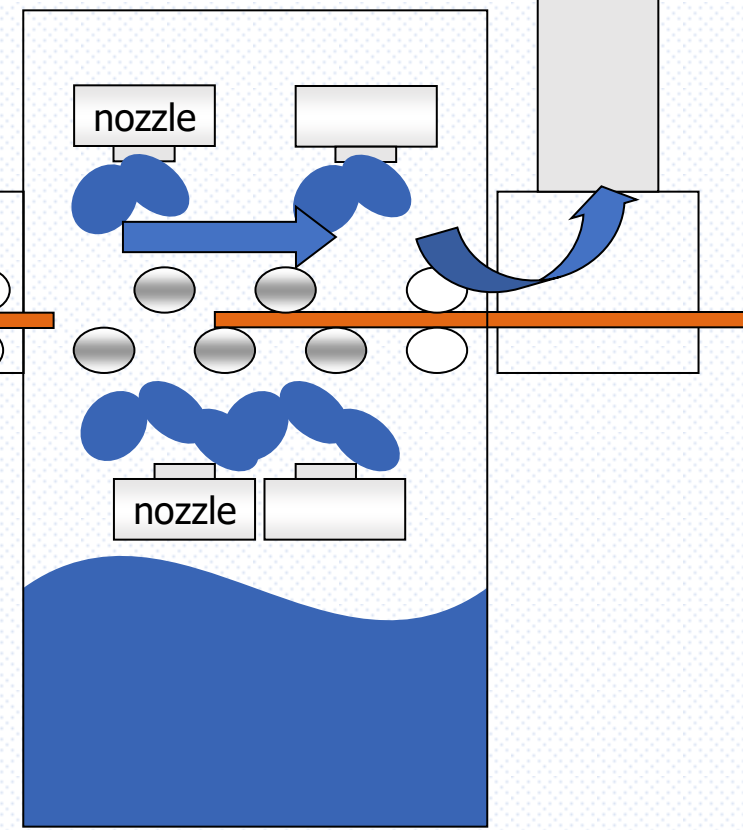
Super Dry

nozzle



Air knife

nozzle



Water rinse





Own Brand Equipment - Retrospect and Prospect

2025 H1 Retrospect and Prospect



1. In the first half of 2025, the primary applications of our self-developed equipment will continue to be mainly in substrates, HDI, and SLP (Substrate-like PCBs). The target markets include high-speed computing, electric vehicles (EV), advanced driver-assistance systems (ADAS), as well as high-speed networking and low-orbit satellite wireless communications, all of which reflect high-value market trends.
2. At TPCA Show 2025 (October 22–24), in addition to showcasing our patented 7A products and glass substrate equipment, our ECO Heat Recovery System stood out among fierce competition from over 500 companies. With our independent R&D capabilities, we proudly won the 23rd Golden Peak Award for “Top Ten Outstanding Innovation and R&D.” This system significantly contributes to the global trend of energy conservation and carbon/waste reduction, supporting customers in achieving sustainability goals.
3. As customers expand their production to Southeast Asia, Ampoc Technology has established a Thailand subsidiary to ensure close communication, provide after-sales services, and capture emerging business opportunities.
4. Regardless of global circumstances, continuously developing new technologies to meet customer needs is our way of survival!

2025 H1 Retrospect and Prospect



Future Equipment R&D and Market Outlook

- Demand for equipment related to thick large panels, advanced substrates, and future glass substrate processes.
- Increasing competition among PCB manufacturers entering the high-end product market, driving future demand for equipment in 5G-related substrates, SLP (Substrate-like PCBs), HDI, and flexible boards.
- Growing demand for PCB equipment in smart electric vehicles and safety-related applications.
- Ongoing R&D of energy-saving, waste-reducing, and cleanroom-compatible equipment.

05

Distribution Business - Introduction and Prospect

Advance package/Material/Inspect solution





Target & Planning



➤ 2025 Directions and Layout :

◆ Directions: :

- Advanced packaging process materials & equipment (COWOS / COWOP / Bonding / Inspection)
- Lithography Process Materials Adopted by Domestic and Overseas Manufacturers

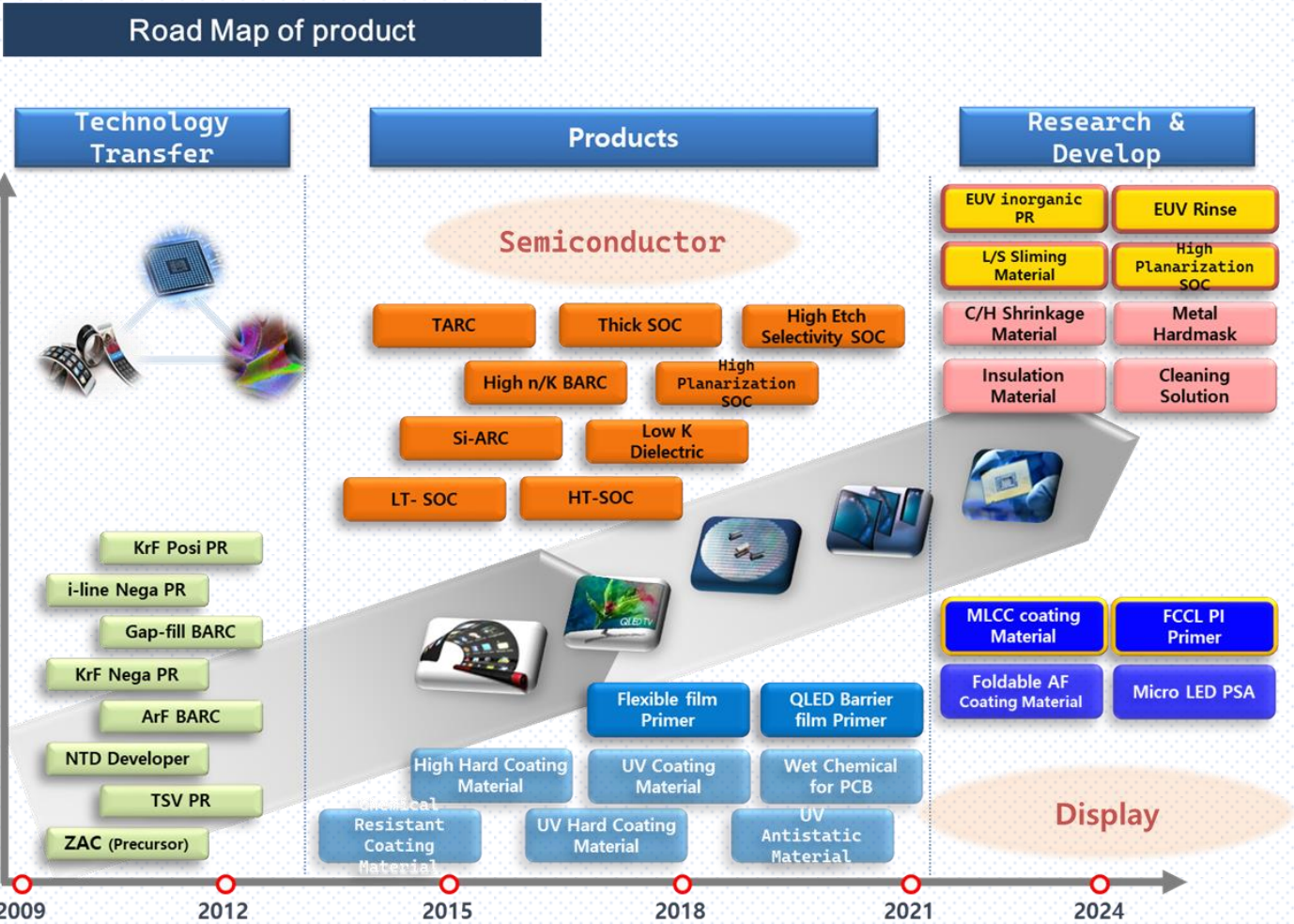
■ Materials

- Advanced packaging process materials
- Micro Bumping / SnAg (already in mass production for customers)
- Cu Pillar (already in mass production for customers)
- Meanwhile, jointly developing next-generation products with customers

■ Lithography Material

- Already obtained customer approval and has entered mass production (production volume scales with customer capacity expansion).
- Currently under testing at semiconductor fabs in Taiwan and overseas.

Lithography Products Overview



■ equipment

● 3D Inspection system (WOSOP/FOPLP)

Function : Used for surface morphology measurement prior to bonding.

Purpose : During advanced packaging processes, variations may occur. This equipment provides large volumes of morphology data after measurement, significantly improving bonding yield.

(Order obtained in 2024 Q4, currently under installation)





■ External Environment Impact — Tariffs and Exchange Rates

Currently, there is no direct impact, but indirect effects require careful attention.

■ Key Strategic Priorities

1. Materials Business: Accelerate the certification process with domestic and overseas semiconductor fabs, with mass production expected to begin in Q4 and contribute to revenue.
2. Equipment Business: Focus on advanced packaging fabs, deepen adoption cases of 3D surface inspection systems, and establish technical barriers and market reputation.
3. Risk Management: Continuously monitor changes in international tariff policies and exchange rate trends, and adjust procurement and pricing strategies accordingly.

Thank you!